



















4	LAYER STUCK-UP				
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.8	
3	Top Layer	Copper	1.20mil		
4	Dielectric 1	FR-4	8.50mil	4.2	
5	GND	Copper	1.20mil		
6	Dielectric 2		40.50mil	4.4	
7	POWER	Copper	1.20mil		
8	Dielectric 3		8.50mil	4.2	
9	Bottom Layer	Copper	1.20mil		
10	Bottom Solder	Solder Resist	0.40mil	3.8	
11	Bottom Overlay				

5	IMPEDANCE TABLE				
LAYER	TRACE (MIL)	SPACEING (MIL)	IMPEDANCE (SINGLE END)	IMPEDANCE (DIFFERENTIAL)	TOLERANCE
1	11	7			
4	11	7	N/A	90 OHM	+/- 10%

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
✕	1	1.500mm (59.06mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn150m155				-	-
◇	1	3.400mm (133.86mil)	NPTH	Square	Top Layer - Bottom Layer	Pad	Rounded	c0hn340m345				-	-
✕	2	0.800mm (31.50mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c50hn80				-	-
■	2	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c180h110m185				-	-
⊕	2	3.500mm (137.80mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320hn350m0mx0				-	-
⊗	3	1.100mm (43.31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn110m115				-	-
⊗	4	1.650mm (64.96mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rectangle	s250h165m255				-	-
✕	4	1.730mm (68.11mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn173m178				-	-
□	4	3.500mm (137.80mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h350m605				-	-
○	8	0.600mm (23.62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r210_140h60_130r100m215_145				1.300mm (51.18mil)	0.700mm (27.56mil)
✱	8	0.900mm (35.43mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn90_250m260_100				2.500mm (98.43mil)	1.600mm (62.99mil)
▽	14	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
▽	20	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
✱	20	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
●	1302	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
1395 Total													

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

NOTES:UNLESS OTHERWISE SPECIFIED

- THIS BOARD WILL CONFORM TO:
IPC-A-600G . CURRENT REV . CLASS ☐
IPC-6012B . CURRENT REV . CLASS ☐
- ALL UNSPECIFIED DIMENSIONS AND TOLERANCES ARE IN MILLIMETER.
- UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.
- MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.
- IMPEDANCE CONTROL (IF APPLICABLE) AND VENDER TO PROVIDE IMPEDANCE PATTERN COUPON AND TEST REPORT.
SEE IMPEDANCE CONTROL TABLE FOR DETAIL INFORMATION
- BOARD SHALL BE LPI SOLDER MASKED OVER BARE BOTH SIDES PER
COLOR BLUE.
- ALL VIA HOLES SHALL BE COMPLETELY TENTED AND PLUGED.
- SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP ON ANY COMPONENT PAD OR THROUGH HOLE.
COLOR WHITE.
- SURFACE WILL BE FINISHED WITH 1-3 MICRO INCHES IMMERSION GOLD OVER 100 MICRO INCHES NICKEL.
- REMOVE ALL SHAPE EDGES AND BURRS 0.15 MAXIMUM.
- PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE FABRICATING BOARD.